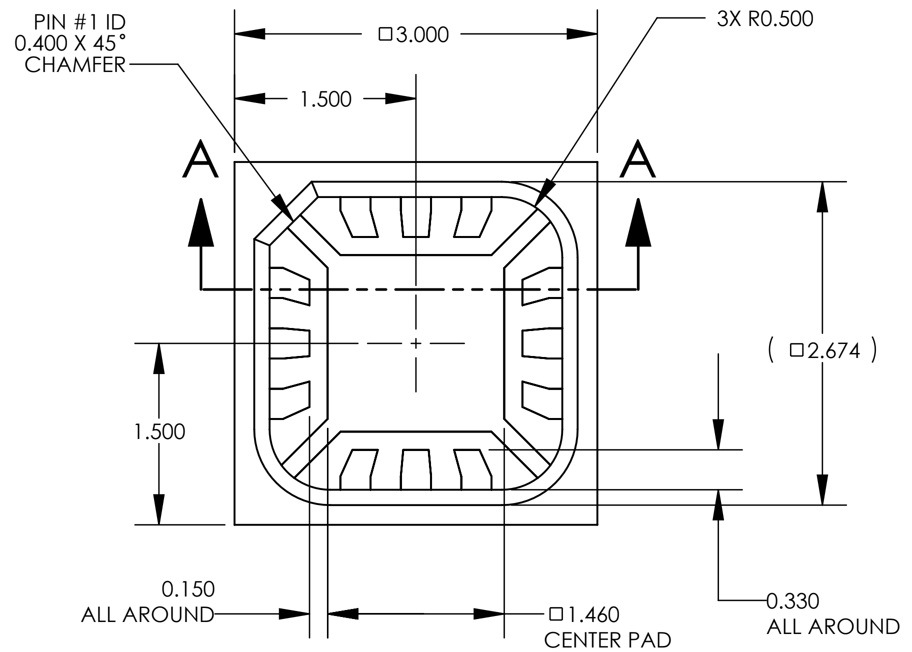
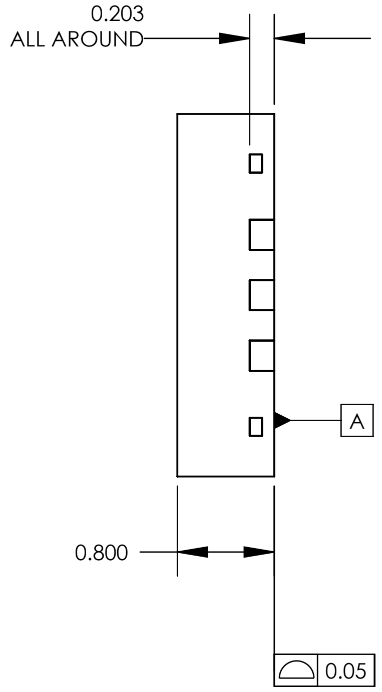
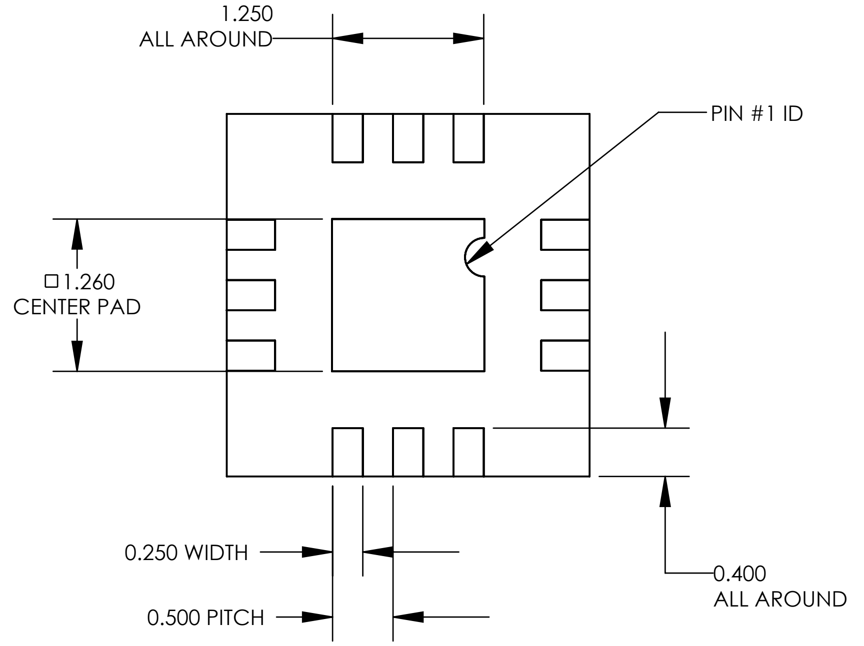
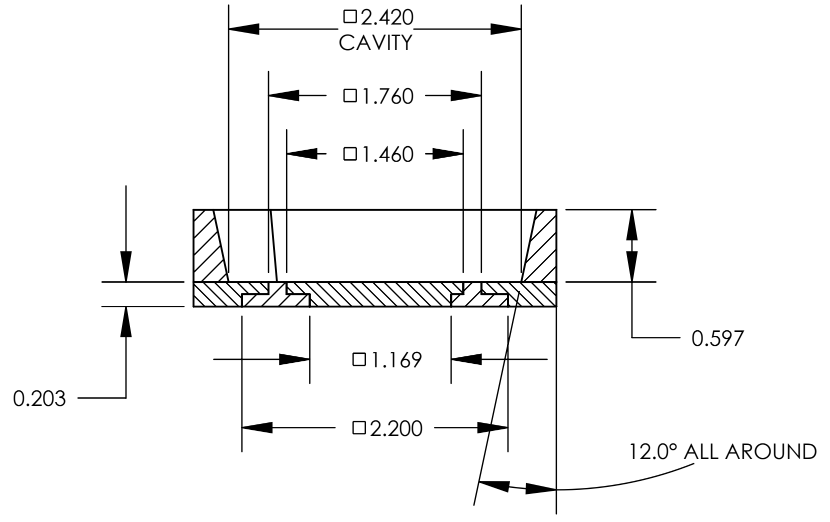


TOP VIEW

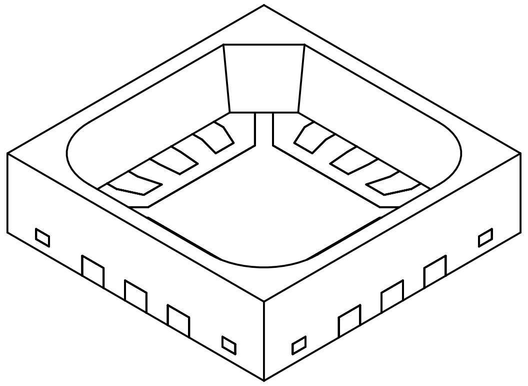




BOTTOM VIEW



SECTION A-A



NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLIGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
   200 TO 300 MICROINCHES (2.5um-7.6um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICROINCHES (1um-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

OPEN·molded
Plastic Package®

PROPRIETARY AND CONFIDENTIAL

NEXT ASSY	USED ON
APPLICATION	

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
ANGULAR: ±0.5 degree
.X = ±0.76 .XX: ±0.25
.XXX = ±0.13 .XXXX = ±0.01

MATERIAL SEE NOTE 1
FINISH SEE NOTE 2
DO NOT SCALE DRAWING

	NAME	DATE
DRAWN	D. Abbe	7/28/11
CHECKED	S. Swen	7/28/11
ENG APPR.	S. Swen	7/28/11

COMMENTS:

QPTECHNOLOGIES
A DIVISION OF PROMEX INDUSTRIES | QPTECHNOLOGIES.COM

TITLE:
QP-QFN12-3MM-0.50MM

SIZE B
DWG. NO. 500370
REV A
SCALE: 16:1
WEIGHT:
SHEET 1 OF 1